



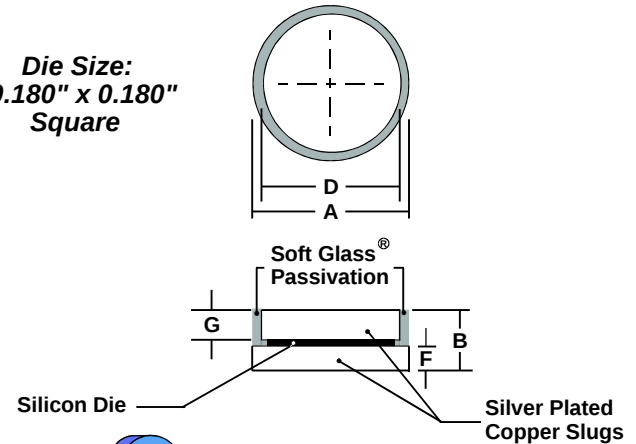
35 AMP OVERVOLTAGE TRANSIENT DISH DIODE

FEATURES

- VOID FREE VACUUM DIE SOLDERING FOR MAXIMUM MECHANICAL STRENGTH AND HEAT DISSIPATION
- PROPRIETARY **SOFT GLASS®** JUNCTION PASSIVATION FOR SUPERIOR RELIABILITY AND PERFORMANCE
- Large die for high power capability
- Very low forward voltage drop
- Built-in stress relief mechanism for die protection
- Silver plated substrates for corrosion resistance and superior soldeability
- Soldering temperature: 250 °C maximum
- Protects expensive automotive electronics and mobile equipment

MECHANICAL SPECIFICATION

Die Size:
0.180" x 0.180"
Square



**SOFT GLASS®
DIODE**

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	5.33	5.46	0.210	0.215
B	2.03	2.16	0.080	0.085
D	4.70	4.83	0.185	0.190
F	0.64	0.76	0.025	0.030
G	0.96	1.09	0.038	0.043

MAXIMUM RATINGS & ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified.

PARAMETER (TEST CONDITIONS)	SYMBOL	RATINGS	UNITS
Series Number		TVS3527D	
Maximum Recurrent Peak Reverse Voltage	VRRM	23	VOLTS
Working Peak Reverse Voltage	VRWM		
Maximum DC Blocking Voltage	VDC		
Breakdown Voltage (IR = 100 mA dc, Tc = 25 °C)	V(BR)	24 Min / 32 Max	
Average Rectified Forward Current (Single phase, Resistive load, 60 Hz)	Io	35	AMPS
Non-repetitive Peak Forward Surge Current (Half wave, Single phase, 60 Hz sine applied to rated load)	IFSM	500	
Repetitive Peak Reverse Surge Current (Time constant = 10 mSec Duty cycle ≤ 1.0%, Tc = 25 °C)	IRSM	110	
Instantaneous Forward Voltage (IF = 80A @300 μSec pulse, Tc = 25°C) Maximum Typical	VF	1.05 1.00	VOLTS
Maximum DC Reverse Current (VR = 20V DC, Tc = 25 °C)	IR	200	nA
Maximum Thermal Resistance, Junction to Lead (Note 1)	RθJC	0.8	°C/W
Junction Operating & Storage Temperature Range	TJ, TSTG	-65 to +175	°C

Notes: 1) Single Side Cooled

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